



PK171 (v1.5) April 26, 2013

100% Material Declaration Data Sheet for VQ44 Package

Average Weight: 0.2677 g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.003341	1.248
	Silicon (Si)	7440-21-3	100.00		0.003341	
Die Attach					0.000921	0.344
	Silver (Ag)	7440-22-4	72.00		0.000663	
	Epoxy Resin	Trade Secret	15.00		0.000138	
	Anhydride	Trade Secret	10.00		0.000092	
	1,4-Butanedioldiglycidyl ether	2425-79-8	3.00		0.000028	
Mold Compound					0.181160	67.681
	Epoxy Resin	Trade secret	7.00		0.012681	
	Phenol Resin	Trade secret	5.00		0.009058	
	Carbon Black	1333-86-4	0.30		0.000543	
	Fused Silica	60676-86-0	87.70		0.158877	
Leadframe					0.077366	28.904
	Copper (Cu)	7440-50-8	98.28		0.076035	
	Chromium (Cr)	7440-47-3	0.25		0.000193	
	Tin (Sn)	7440-31-5	0.25		0.000193	
	Zinc (Zn)	7440-66-6	0.22		0.000170	
	Silver (Ag)	7440-22-4	1.00		0.000774	
Solder Plating					0.003502	1.308
	Tin (Sn)	7440-31-5	85.00		0.002977	
	Lead (Pb)	7439-92-1	15.00		0.000525	
Gold Wire					0.001376	0.514
	Gold (Au)	7440-57-5	99.00		0.001362	
	Palladium	7440-05-3	1.00		0.000014	

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Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
03/16/06	1.0	Initial Xilinx release.
08/04/06	1.1	100% Material Declaration
10/05/06	1.2	Updated Component descriptions
11/18/11	1.3	Updated Component weights and descriptions
08/24/12	1.4	Updated CAS # in Die Attach
04/26/13	1.5	Updated CAS Description in Die Attach

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